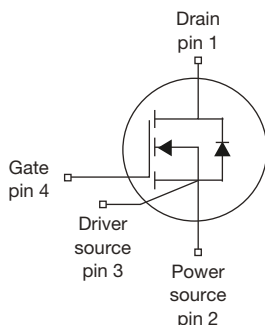
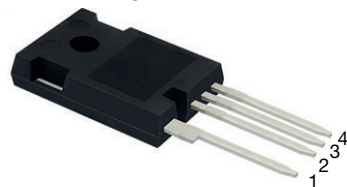


MaxSiC® 1200 V N-Channel SiC MOSFET



RoHS
COMPLIANT
HALOGEN
FREE

TO-247AD 4L

Marking Code: Q120A063SL

PRODUCT SUMMARY

| | | |
|--|-----------------|----|
| V_{DS} (V) at T_J max. | 1200 | |
| $R_{DS(on)}$ typ. (m Ω) at 25 °C | $V_{GS} = 18$ V | 63 |
| Q_g typ. (nC) | 61 | |
| I_D (A) | 39 | |
| C_{oss} typ. (pF) | 70 | |
| P_D (W) | 205 | |
| Configuration | Single | |

ORDERING INFORMATION

| | |
|---------------------------------|-------------------|
| Package | TO-247AD 4L |
| Lead (Pb)-free and halogen-free | MXPQ120A063SL-GE3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|--|----------------|----------------|---------|
| Drain-source voltage | V_{DS} | 1200 | V |
| Gate-source voltage | V_{GS} | -10 / +22 | |
| Recommended operation voltage of gate-source | V_{GSOP} | -5 to -3 / +18 | |
| Continuous drain current | I_D | 39 | A |
| Pulsed drain current ^a | I_{DM} | 78 | |
| Short-circuit withstand time ^b | T_{SC} | 3 | μ s |
| Maximum power dissipation | P_D | 205 | W |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +175 | °C |
| Soldering recommendations (peak temperature) | For 10 s | 260 | °C |
| Single pulse avalanche energy ^c | E_{AS} | 162 | mJ |

Notes

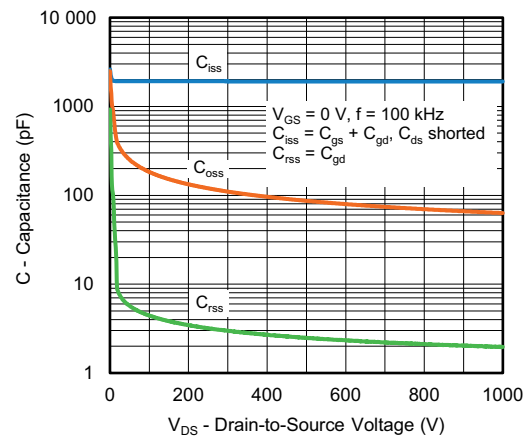
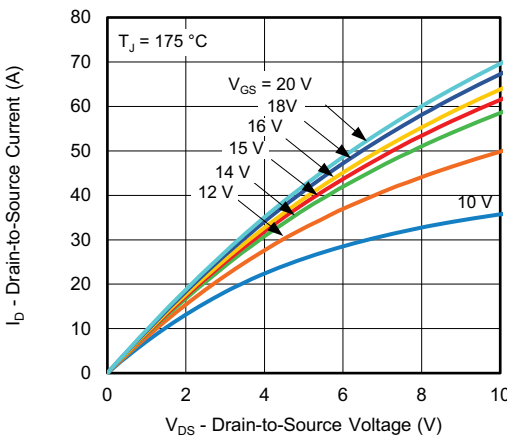
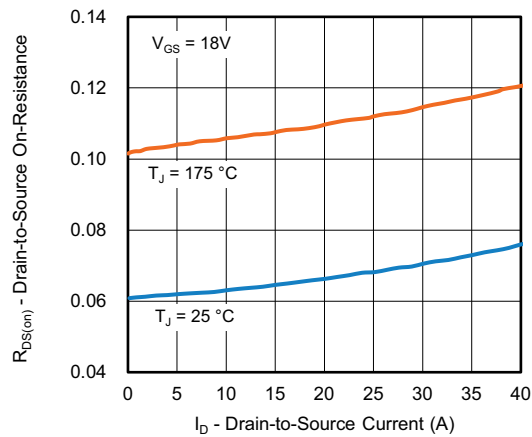
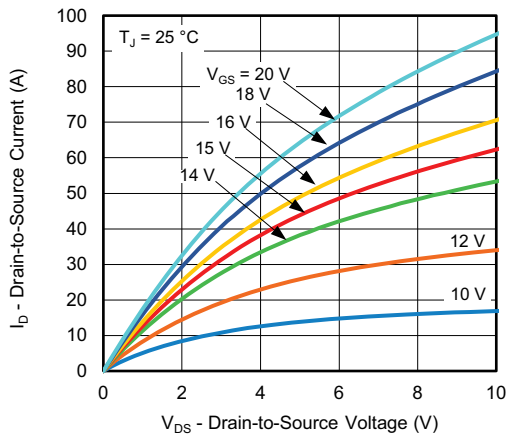
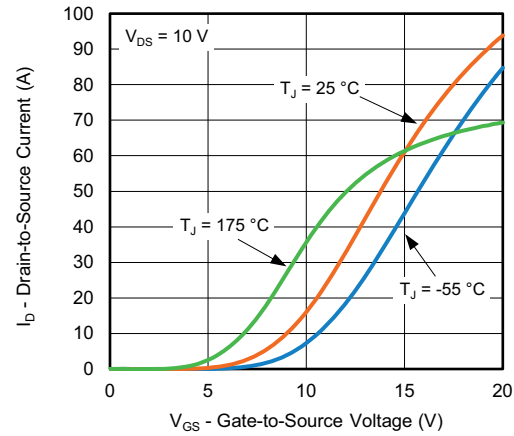
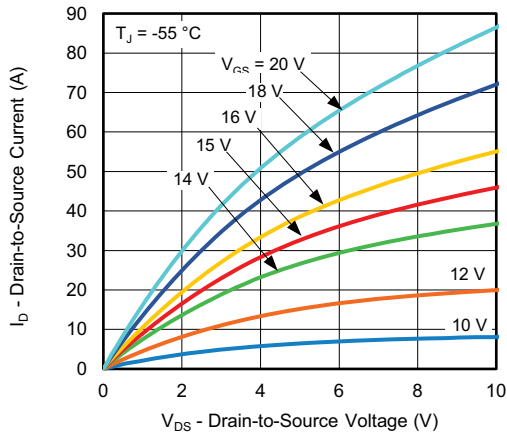
- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{GS} = 18$ V, $V_{DS} = 800$ V, $R_{g(ext)} = 20$ Ω , verified by the design / characterization
- $T_J = 25$ °C, $V_{DD} = 120$ V, $L = 1$ mH, $V_{GS} = 18$ V, $I_{AS} = 18$ A, verified by the design / characterization

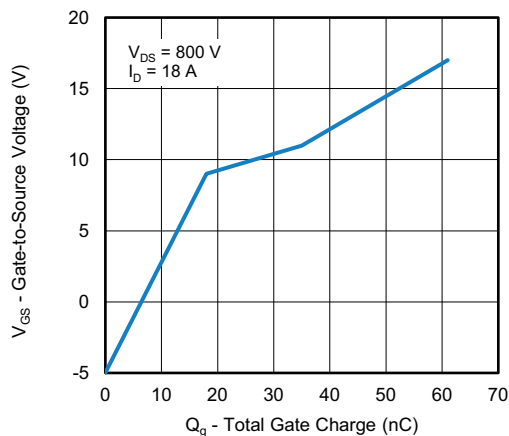
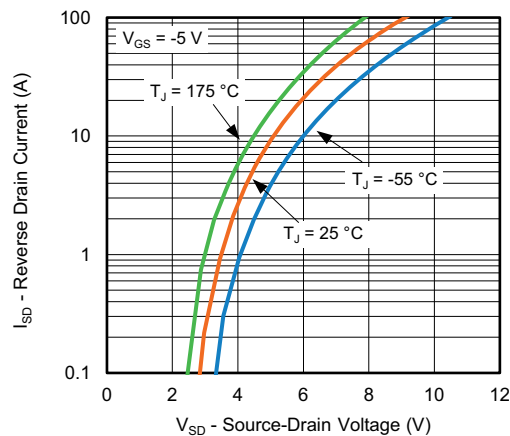
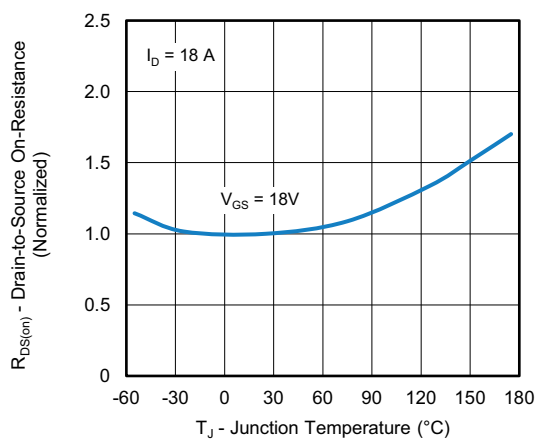
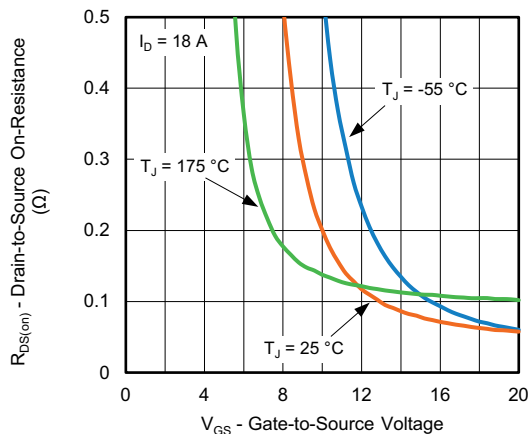
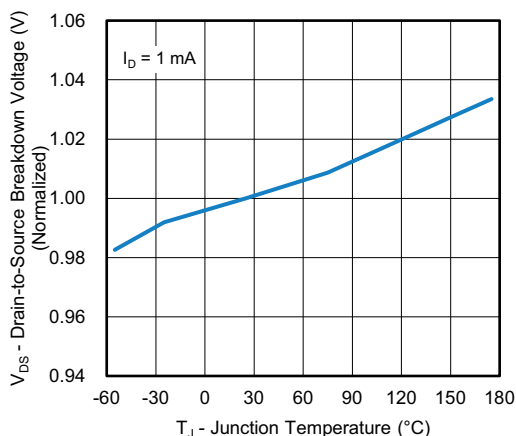
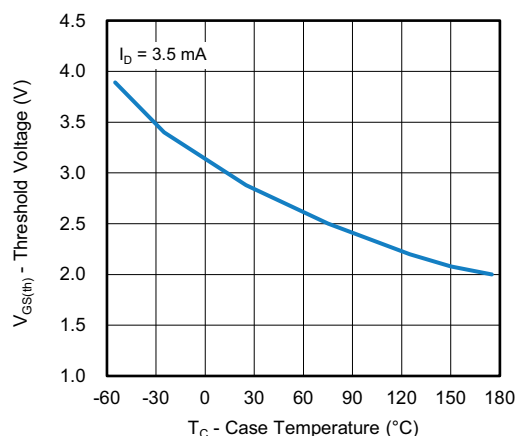
THERMAL RESISTANCE RATINGS

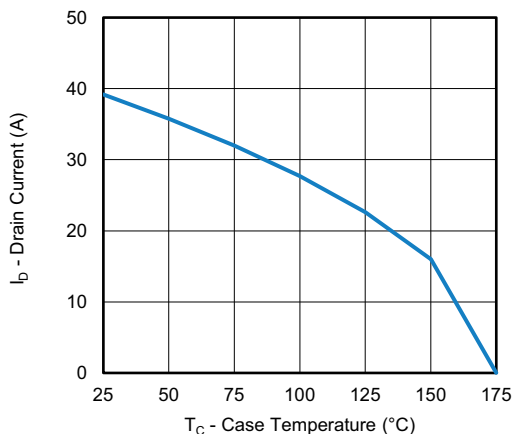
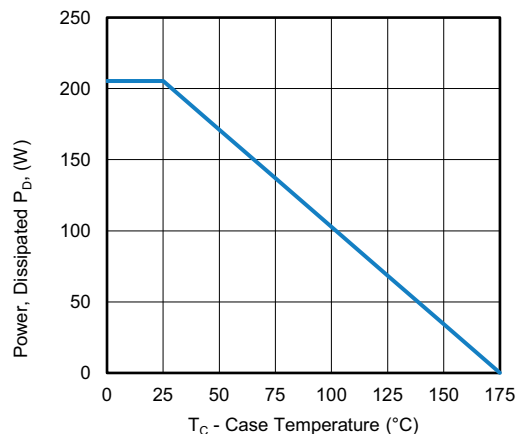
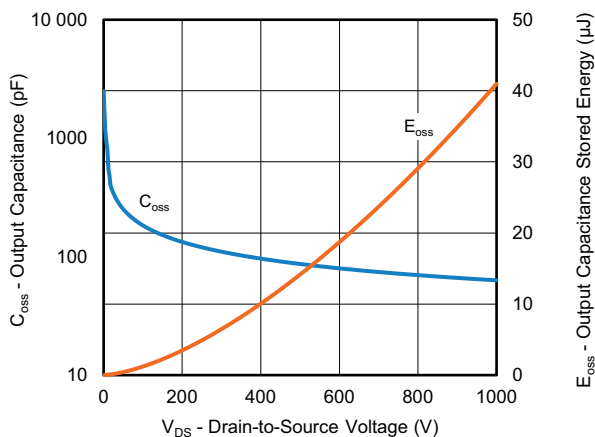
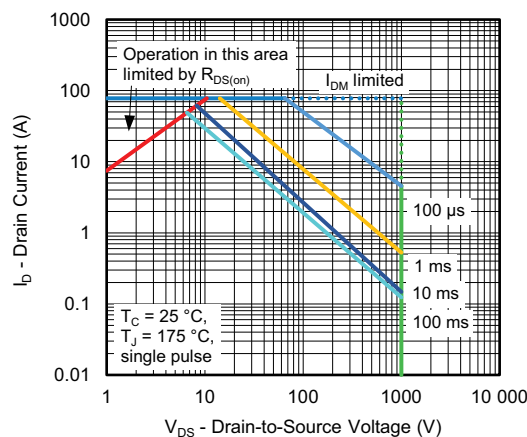
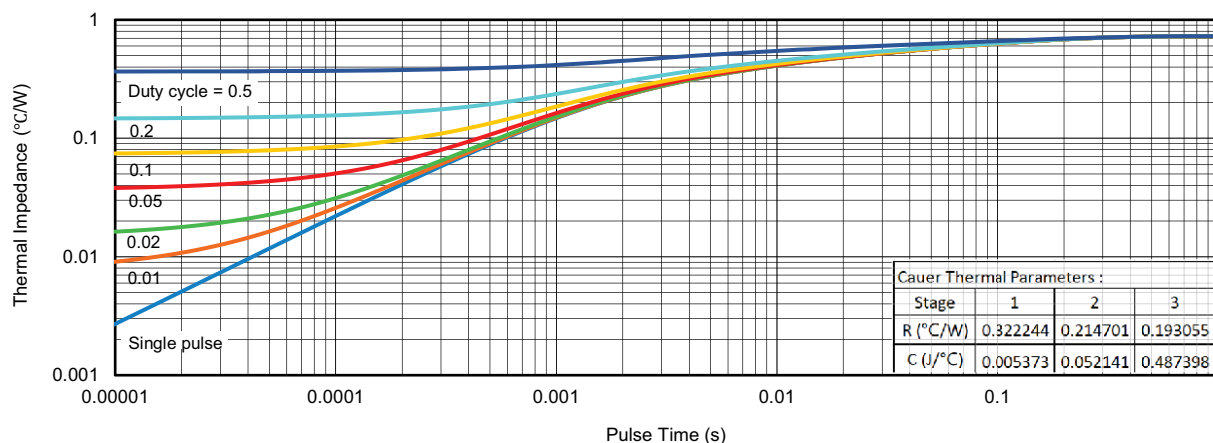
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum junction-to-ambient | R_{thJA} | - | 40 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 0.73 | |

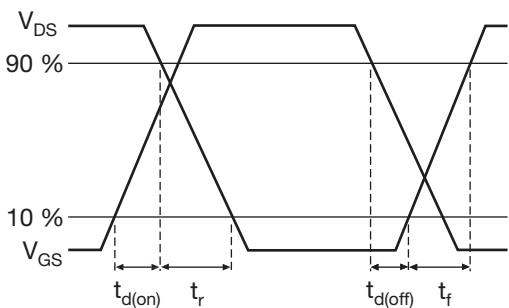
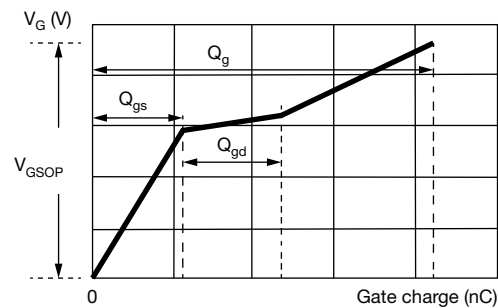
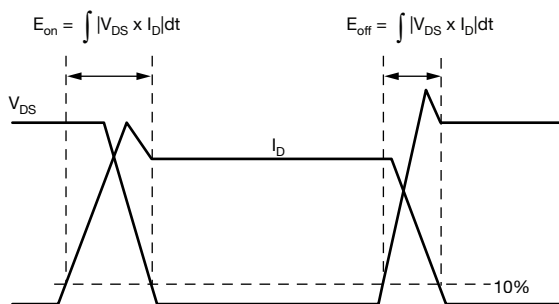
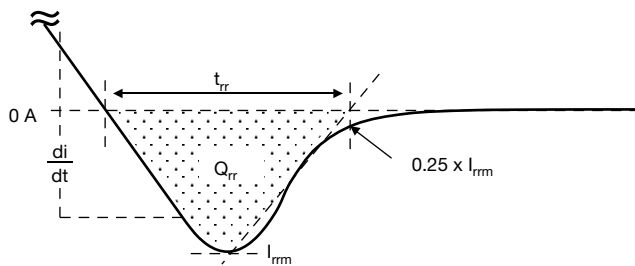
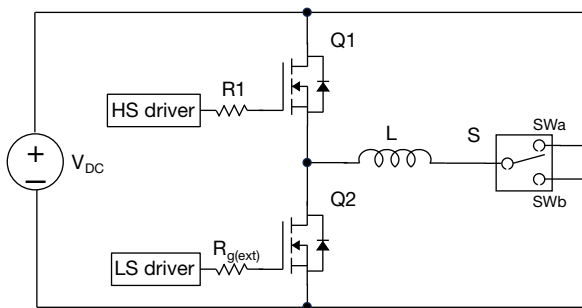
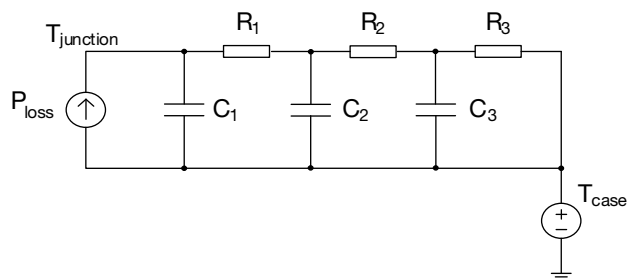


| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | | |
|---|---------------------|--|-------------------------|------|------|------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 1 mA | | 1200 | - | - | V |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 3.5 mA | | - | 2.9 | - | V |
| | | V _{DS} = V _{GS} , I _D = 3.5 mA, T _J = 175 °C | | - | 2.0 | - | V |
| Gate-source leakage | I _{GSS} | V _{GS} = 22 V, V _{DS} = 0 V | | - | - | 100 | nA |
| | | V _{GS} = -10 V, V _{DS} = 0 V | | - | - | -100 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 1200 V, V _{GS} = 0 V | | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 15 V, I _D = 18 A | | - | 75 | 94 | mΩ |
| | | V _{GS} = 18 V, I _D = 18 A | | - | 63 | 79 | |
| | | V _{GS} = 18 V, I _D = 18 A, T _J = 175 °C | | - | 107 | - | |
| Transconductance | g _{fs} | V _{DS} = 10 V, I _D = 18 A | | - | 7 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 800 V, f = 100 KHz | | - | 1909 | - | pF |
| Output capacitance | C _{oss} | | | - | 70 | - | |
| Reverse transfer capacitance | C _{rss} | | | - | 2 | - | |
| Total gate charge | Q _g | V _{GS} = -5 V ~ 18 V, I _D = 18 A, V _{DS} = 800 V | | - | 61 | - | nC |
| Gate-source charge | Q _{gs} | | | - | 18 | - | |
| Gate-drain charge | Q _{gd} | | | - | 17 | - | |
| Gate Resistance | R _g | V _{DS} = 0 V, f = 1 MHz | | - | 3 | - | Ω |
| Switching Characteristics | | | | | | | |
| Turn-on delay time | t _{d(on)} | V _{GS} = -5 V ~ 18 V, I _D = 18 A, V _{DS} = 800 V, R _{g(ext)} = 4.4 Ω | T _J = 25 °C | - | 17 | - | ns |
| Rise time | t _r | | T _J = 175 °C | - | 15 | - | |
| | | | T _J = 25 °C | - | 14 | - | |
| | | | T _J = 175 °C | - | 13 | - | |
| | | | T _J = 25 °C | - | 21 | - | |
| Turn-off delay time | t _{d(off)} | | T _J = 175 °C | - | 23 | - | |
| Fall time | t _f | | T _J = 25 °C | - | 10 | - | μJ |
| | | | T _J = 175 °C | - | 10 | - | |
| Turn-on switching energy | E _{on} | | T _J = 25 °C | - | 175 | - | |
| | | | T _J = 175 °C | - | 151 | - | |
| Turn-off switching energy | E _{off} | | T _J = 25 °C | - | 57 | - | |
| | | | T _J = 175 °C | - | 56 | - | |
| Body Diode Ratings and Characteristic | | | | | | | |
| Forward diode voltage | V _{SD} | V _{GS} = -5 V, I _{SD} = 9 A, T _J = 25 °C | | - | 4.8 | - | V |
| Continuous diode forward current | I _{SD} | V _{GS} = -5 V, T _J = 25 °C | | - | - | 29 | A |
| Pulsed diode forward current | I _{SDM} | | | - | - | 78 | |
| Reverse recovery time | t _{rr} | V _{GS} = -5 V, I _{SD} = 18 A, V _R = 800 V, di/dt = 1000 A/μs | | - | 18 | - | ns |
| Reverse recovery charge | Q _{rr} | | | - | 60 | - | nC |
| Reverse recovery current | I _{RRM} | | | - | 6 | - | A |

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 10 - Typical Source-Drain Diode Forward Voltage

Fig. 8 - Normalized On-Resistance vs. Temperature

Fig. 11 - On-Resistance vs. Gate-to-Source Voltage

Fig. 9 - Drain-to-Source Voltage vs. Temperature

Fig. 12 - Threshold Voltage vs. Case Temperature


Fig. 13 - Drain Current vs. Case Temperature

Fig. 15 - Power, Dissipated P_D vs. Case Temperature

Fig. 14 - Output Capacitance and its Stored Energy vs. Drain-to-Source Voltage

Fig. 16 - Safe Operating Area

Fig. 17 - Transient Thermal Impedance


Fig. 18 - Waveforms of Switching Time

Fig. 21 - Waveforms for Gate Charge

Fig. 19 - Waveforms for Switching Energy

Fig. 22 - Waveforms for Reverse Recovery

Fig. 20 - Switching and Reverse Diode Characteristics Measurement Circuit

Fig. 23 - Thermal Equivalent Circuit

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